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Perfect solutions through:

Separation of long, thin workpieces

The separation of long, thin workpieces (cylinder spikes, axles etc.) through vibratory separation encounters the problem that Grinding or polishing chips are bigger than the workpiece diameter. During the separation process the workpiece can stand up and fall through the screening sieve together with the grinding or polishing chips.

In this case, several separation processes are necessary. This is time consuming and costly.



Picture 1: CF 18 with Unisepa

On request, OTEC can integrate a new attachment to the Unisepa, which prevents the long thin workpieces from standing up. A 100% separation without repeat of the separation process is possible.



Picture 2 and 3: new device as addition to the Unisepa for the separation of long, thin workpieces

For further information please do not hesitate to contact Mr. Helmut Gegenheimer , phone + 49 (0) 7082- 49 11 20

Keyword: Separation of long, thin workpieces.

Preview:

Visit us at the NORDTEC in Hamburg from 23.-26.01.2008, Hall A4 Booth 113